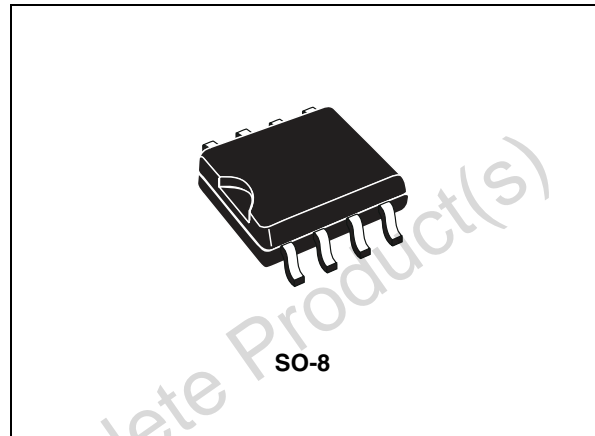


## Enhanced power switch

Not recommended for new design

### Features

- 90 mΩ high-side MOSFET switch
- 500 mA continuous current per channel
- Thermal and short-circuit protection with overcurrent logic output
- Operating range from 2.7 to 5.5 V
- CMOS- and TTL-compatible enable inputs
- 2.5 ms typical rise time
- Undervoltage lock out
- 10 μA maximum standby supply current
- Ambient temperature range, 0 °C to 85 °C
- 2 kV ESD protection
- Fault-blanking



**Table 1. Device summary**

Order code	Package	Packaging
ST2041BDR <sup>(1)</sup>	SO-8	Tape and reel

1. Not recommended for new design (refer to STMPS2141MTR). Contact ST sales office for availability.

# Contents

<b>1</b>	<b>Description</b> .....	<b>3</b>
<b>2</b>	<b>Schematic diagram and pin connections</b> .....	<b>4</b>
<b>3</b>	<b>Functional descriptions</b> .....	<b>5</b>
3.1	Fault-blanking .....	5
3.2	Overcurrent/overtemperature protection .....	5
3.3	Undervoltage lock out (UVLO) .....	5
<b>4</b>	<b>Maximum rating</b> .....	<b>6</b>
	Recommended operating conditions .....	6
<b>5</b>	<b>Electrical characteristics</b> .....	<b>7</b>
<b>6</b>	<b>Package mechanical data</b> .....	<b>10</b>
<b>7</b>	<b>Revision history</b> .....	<b>12</b>

Obsolete Product(s) - Obsolete Product(s)

# 1 Description

The ST2041 power distribution switch is intended for applications where heavy capacitive loads and short-circuits are likely to be encountered. These devices incorporate 90 mΩ N-channel MOSFET high-side power switches for power-distribution. The switch is controlled by a logic enable input. Gate drive is provided by an internal charge pump designed to control the power-switch rise times and fall times to minimize current surges during switching. The charge pump requires no external components and allows operation from supplies as low as 2.7 V.

When the output load exceeds the current-limit threshold or a short is present, the device limits the output current to a safe level by switching into a constant-current mode, pulling the overcurrent logic output low. When continuous heavy overloads and short-circuits increase the power dissipation in the switch, causing the junction temperature to rise, a thermal protection circuit shuts off the switch to prevent damage. Recovery from a thermal shutdown is automatic once the device has cooled sufficiently. Internal circuitry ensures the switch remains off until valid input voltage is present.

## 2 Schematic diagram and pin connections

Figure 1. Schematic diagram

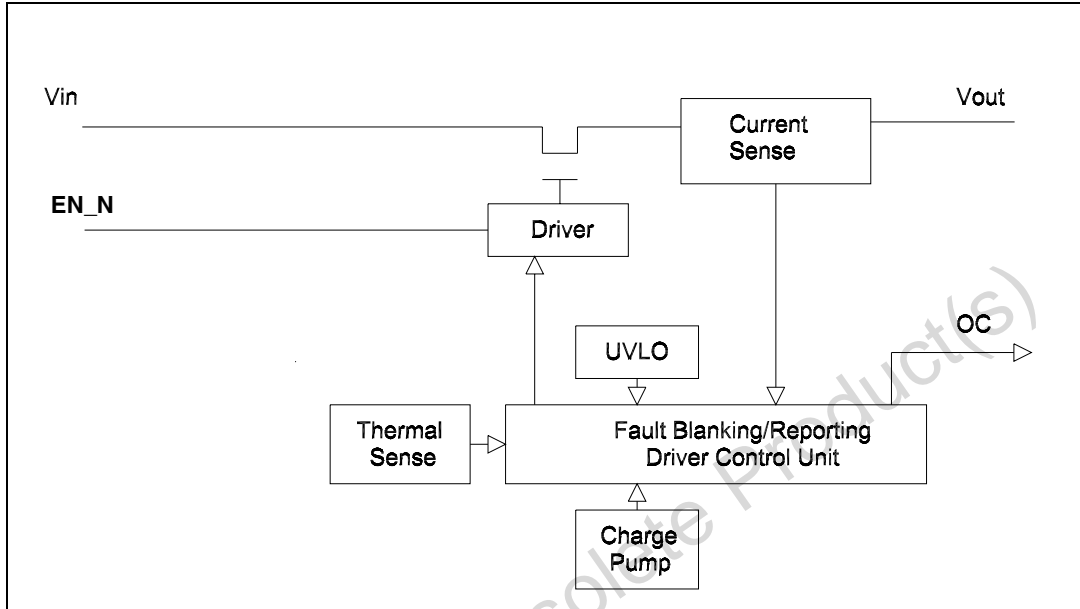


Figure 2. Pin connections (top view)

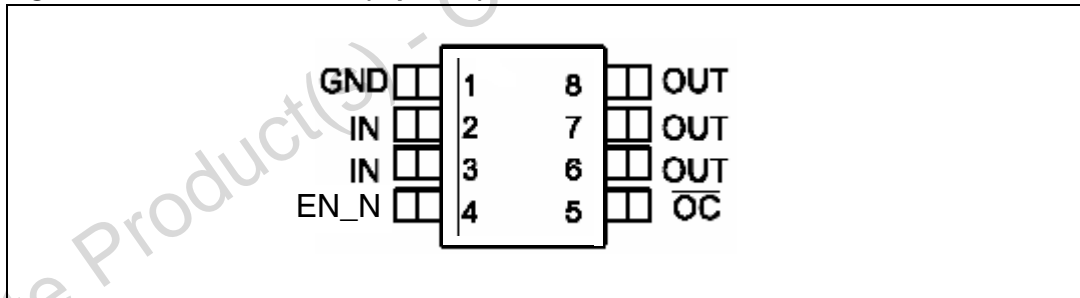


Table 2. Pin functions

Pin	Name	Type	Description
1	GND	-	Ground
2	IN1	-	V <sub>CC</sub> input, 2.7-5.5 V
3	IN2	-	V <sub>CC</sub> input, 2.7-5.5 V
4	EN_N	I	Enable (active low)
5	OC	O	Open drain output for fault indication
6	OUT3	-	Output
7	OUT2	-	Output
8	OUT1	-	Output

## 3 Functional descriptions

### 3.1 Fault-blanking

ST devices feature a 10 ms fault-blanking. Fault-blanking allows current-limit faults, including momentary short-circuit faults that occur when hot-swapping a capacitive load, and also ensures that no fault is issued during power-up. When a load transient causes the device to enter current limit, an internal counter starts. If the load fault persists beyond the 10 ms fault-blanking timeout, the FAULT output asserts low. Load-transient faults less than 10 ms (typical) will not cause a FAULT output assertion. Only current-limit faults are blanked. Die overtemperature faults and input voltage drops below the undervoltage lock out (UVLO) threshold will cause an immediate fault output.

### 3.2 Overcurrent/overtemperature protection

In overcurrent or short-circuit condition, the switch limits the current at 500 mA. If temperature of die goes above limit value, the switch turns OFF.

### 3.3 Undervoltage lock out (UVLO)

When input voltage drops below critical value, the power switch turns OFF to prevent improper operation due to low voltage.

## 4 Maximum rating

Stressing the device above the rating listed in the “Absolute maximum ratings” table may cause permanent damage to the device. These are stress ratings only, and operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics™ SURE program and other relevant quality documents.

**Table 3. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_I$	Input voltage range	-0.3-6.0	V
$V_O$	Output voltage range	-0.3-( $V_I+0.3$ )	V
$V_{IENX}$	EN input voltage range	-0.3-6.0	V
$I_O$	Continuous output current	Internally limited	
ESD	ESD protection level	2	kV
$T_J$	Junction operating temperature	-40 to 125	°C
$T_{STG}$	Storage temperature	-55 to 150	°C

## Recommended operating conditions

**Table 4. Recommended operating conditions**

Symbol	Parameter	Min	Typ	Max	Unit
$V_I$	Input voltage	2.7	5.0	5.5	V
$V_O$	Output voltage	0	5.0	5.5	V
$I_O$	Continuous output current	0	-	500	mA

## 5 Electrical characteristics

Table 5. Electrical characteristics ( $T_J = 25\text{ °C}$ ,  $V_I = 5.0\text{ V}$ )

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$R_{DS(on)}$	Static drain-source on-state resistance	$V_I = 3.3\text{ V}$ $-40 < T_J < 125\text{ °C}$		100	145	m $\Omega$
		$V_I = 5.0\text{ V}$ $-40 < T_J < 125\text{ °C}$		90	135	
		$V_I = 3.3\text{ V}$ $T_J = 25\text{ °C}$		90	130	
		$V_I = 5.0\text{ V}$ $T_J = 25\text{ °C}$		80	110	
$t_r$	Output rise time <sup>(1)</sup>	$V_I = 5.5\text{ V}$ $R_L = 10\ \Omega$ $C_L = 1\ \mu\text{F}$		2.5		ms
		$V_I = 2.7\text{ V}$ $R_L = 10\ \Omega$ $C_L = 1\ \mu\text{F}$		3		ms
$t_f$	Output fall time <sup>(1)</sup>	$V_I = 5.5\text{ V}$ $R_L = 10\ \Omega$ $C_L = 1\ \mu\text{F}$		0.3		ms
		$V_I = 2.7\text{ V}$ $R_L = 10\ \Omega$ $C_L = 1\ \mu\text{F}$		0.2		ms
$T_{ON}$	Turn-on time <sup>(1)</sup>	$R_L = 10\ \Omega$ $C_L = 100\ \mu\text{F}$			20	ms
$T_{OFF}$	Turn-off time <sup>(1)</sup>	$R_L = 10\ \Omega$ $C_L = 100\ \mu\text{F}$			40	ms

1. Not tested in production, specified by design.

**Table 6. Current limit characteristics ( $V_I = 5.5\text{ V}$ ,  $I_O = \text{rated current}$ ,  $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)**

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$I_{OS}$	Short-circuit output current	$V_I = 5\text{ V}$ OUT connected to GND, device enabled into short-circuit	0.7	1.0	1.3	A

**Table 7. Supply current characteristics ( $V_I = 5.5\text{ V}$ ,  $I_O = \text{rated current}$ ,  $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)**

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$I_{OFF}$	Switch turned OFF	No load		1.0	5.0	$\mu\text{A}$
		No load; $-40 < T_J < 125\text{ }^\circ\text{C}$			10	$\mu\text{A}$
$I_{ON}$	Switch turned ON	No load		70	90	$\mu\text{A}$
		No load; $-40 < T_J < 125\text{ }^\circ\text{C}$			100	$\mu\text{A}$
$I_{leakage}$	Output leakage current	Output grounded, switch is OFF			10	$\mu\text{A}$
		Output grounded, switch is OFF; $-40 < T_J < 125\text{ }^\circ\text{C}$			20	$\mu\text{A}$

**Table 8. Thermal characteristics ( $V_I = 5.5\text{ V}$ ,  $I_O = \text{rated current}$ ,  $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)**

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
T1	Thermal shutdown threshold		135			$^\circ\text{C}$
T2	Recovery from thermal shutdown		125			$^\circ\text{C}$
Hyst	Hysteresis			10		$^\circ\text{C}$

**Table 9. UVLO characteristics ( $V_I = 5.5\text{ V}$ ,  $I_O = \text{rated current}$ ,  $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)**

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$V_{UVLO}$	Undervoltage lockout threshold		2.0		2.5	V
Hyst	Hysteresis			100		mV

**Table 10. OC pin characteristics ( $V_I = 5.5\text{ V}$ ,  $I_O = \text{rated current}$ ,  $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)**

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
OC blanking	OCx assertion and de-assertion <sup>(1)</sup>		4	8	15	mS
$V_O$	Output low voltage				0.4	V
$I_{OFF}$	OFF current				1.0	$\mu\text{A}$

1. Not tested in production, specified by design.



**Table 11. EN\_N pin characteristics ( $V_I = 5.5\text{ V}$ ,  $I_O = \text{rated current}$ ,  $T_J = 25\text{ °C}$ , unless otherwise specified)**

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$V_{IH}$	High level input voltage	$V_I = 2.7\text{ to }5.5\text{ V}$	2.0			V
$V_{IL}$	Low level input voltage	$V_I = 4.5\text{ to }5.5\text{ V}$			0.8	V
		$V_I = 2.7\text{ to }4.5\text{ V}$			0.4	V
$I_I$	Input current	$V_{IENX} = 0\text{ V or }V_I$	-0.5		0.5	$\mu\text{A}$

Obsolete Product(s) - Obsolete Product(s)

## 6 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK<sup>®</sup> is an ST trademark.

Obsolete Product(s) - Obsolete Product(s)

Figure 3. SO-8 package outline

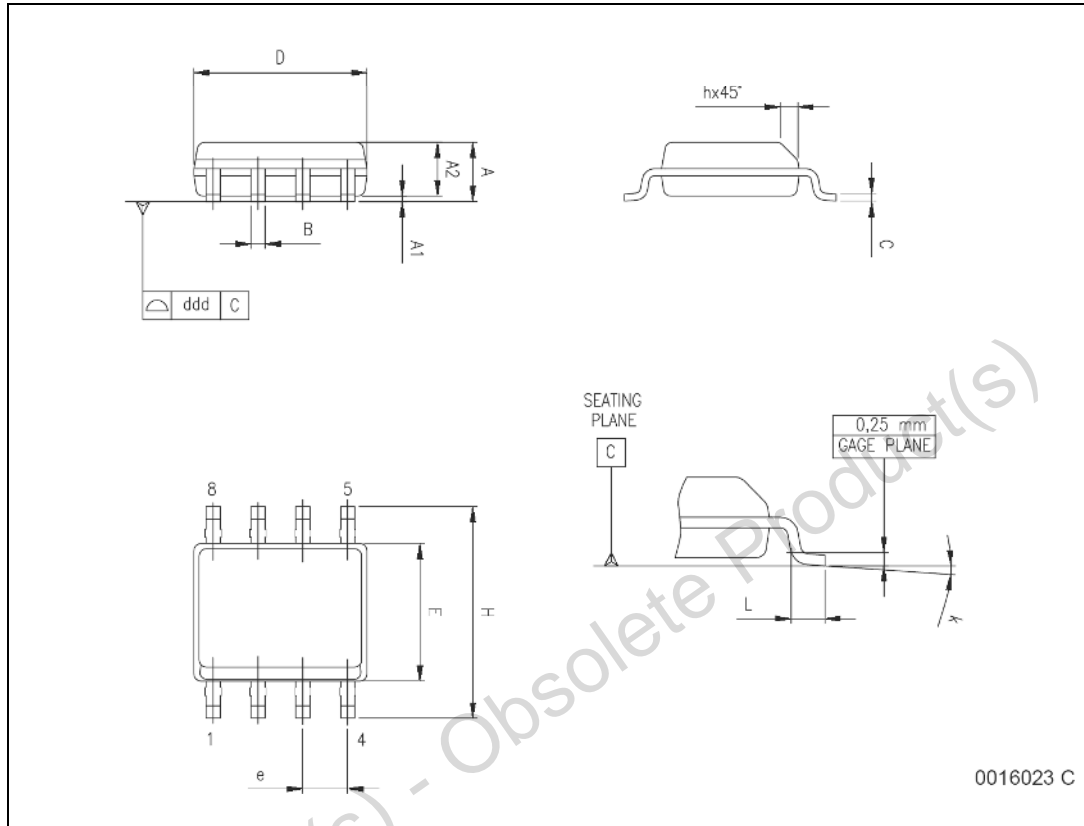


Table 12. SO-8 mechanical data

Symbol	Millimeters			inches		
	Min	Typ	Max	Min	Typ	Max
A	1.35		1.75	0.053		0.069
A1	0.10		0.25	0.004		0.010
A2	1.10		1.65	0.043		0.065
B	0.33		0.51	0.013		0.020
C	0.19		0.25	0.007		0.010
D	4.80		5.00	0.189		0.197
E	3.80		4.00	0.15		0.157
e		1.27			0.050	
H	5.80		6.20	0.228		0.244
h	0.25		0.50	0.010		0.020
L	0.40		1.27	0.016		0.050
k	8° (max.)					
ddd			0.10			0.004

## 7 Revision history

**Table 13. Document revision history**

Date	Revision	Changes
05-May-2006	1	Initial release.
20-Feb-2008	2	Document restructured and converted to new ST template, watermark removed.
24-Nov-2010	3	Document reformatted, added "Not Recommended for New Design" and <i>Note 1</i> below <i>Table 1</i> , updated ECOPACK <sup>®</sup> text in <i>Section 6</i> , corrected typo in <i>Features, Section 1, Table 2, Section 3, Section 4, Table 3, Table 5</i> to <i>Table 11</i> .

**Please Read Carefully:**

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

**UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.**

**UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED ST REPRESENTATIVE, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.**

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2010 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

[www.st.com](http://www.st.com)